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Bv:

Date: 166 26, 200 >

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant

: Robert-Christian Hagen et al.

Applic. No.

: 09/993,266

Filed

: November 19, 2001

Title

: Electronic Component with Shielding and

Method for its Production

PRELIMINARY AMENDMENT

Hon. Commissioner of Patents and Trademarks, Washington, D. C. 20231

Sir:

Preliminary to examination, kindly amend the above-identified application as follows:

In the Claims:

Claim 13 (amended). A method for producing electronic components with shielding, which comprises the steps of:

providing a semiconductor wafer functioning as a semiconductor substrate formed of a semiconductor material and having an